(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
14 January 2010 (14.01.2010)

PCT

(10) International Publication Number
WO 2010/005307 A1

(51) International Patent Classification:
B28D 5/00 (2006.01) *B28D 5/02* (2006.01)

(21) International Application Number:
PCT/NL2009/050414

(22) International Filing Date:
9 July 2009 (09.07.2009)

(25) Filing Language: Dutch

(26) Publication Language: English

(30) Priority Data:
2001790 11 July 2008 (11.07.2008) NL

(71) Applicant *(for all designated States except US)*: **FICO B.V.** [NL/NL]; Ratio 6, NL-6921 RW Duiven (NL).

(72) Inventors; and

(75) Inventors/Applicants *(for US only)*: **IN 'T VELD, Frederik, Hendrik** [NL/NL]; Fintstraat 24, NL-5306 GH Brakel (NL). **HERMANS, Mark** [NL/NL]; Coreanna 111, NL-4191 DC Geldermalsen (NL). **HARMSEN, Wilhelmus, Hendrikus, Johannes** [NL/NL]; Akkerstraat 8, NL-7031 AM Wehl (NL). **ZWEERS, Johannes, Gerhardus, Augustinus** [NL/NL]; Cingelwal 20, NL-7031 CD Wehl (NL).

(74) Agent: **VAN DEN HEUVEL, Henricus, Theodorus**; Patentwerk B.V., P.O. Box 1514, NL-5200 BN 's-Hertogenbosch (NL).

(81) Designated States *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PE, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Declarations under Rule 4.17:

[Continued on next page]

(54) Title: DEVICE AND METHOD FOR SAWING ELECTRONIC COMPONENTS

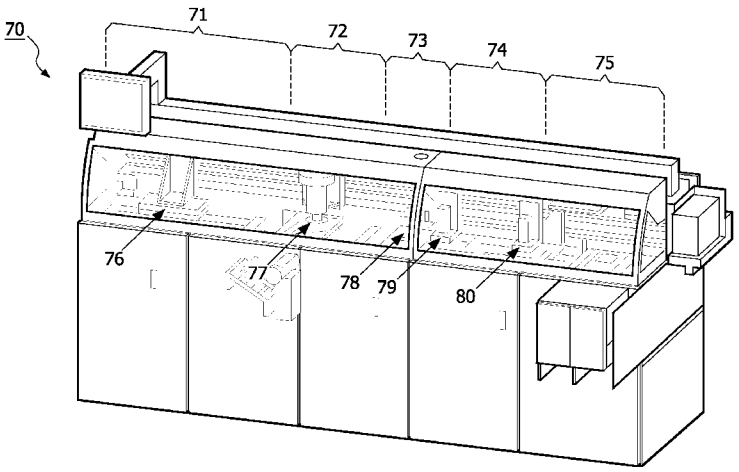


FIG. 3

(57) Abstract: The invention relates to a device for separating electronic components (2), provided with: sawing means (A) and positioning means (B), wherein between the positioning means (B) and the sawing means (A) at least one transfer position (5) is defined for the purpose of transferring positioned electronic components (2). The invention further comprises a separating device (1) for electronic components (2), provided with: sawing means (A), inspection means (D) and sorting means (E), wherein between the inspection means and the sorting means at least one transfer position (36) is defined for the purpose of transferring separated electronic components (2). Finally, the invention also relates to a method for separating electronic components (2).

WO 2010/005307 A1

— *as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))*

Published:

— *with international search report (Art. 21(3))*